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Attorney Docket No.: 70257/40535-RE-C

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Daniel F. Baldwin, et al.

U.S.S.N. 10/082,004

GROUP ART UNIT: 1764

FILED: February 22, 2002

EXAMINER: Not Yet Known

FOR: SUPERMICROCELLULAR FOAMED MATERIALS

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on July 19, 2002.

By:

Donna R. Davis

Commissioner for Patents  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

In connection with the above-identified application, Applicant(s) hereby cite(s) the documents listed on the attached PTO Form 1449. This application relies, under 35 U.S.C. § 120, on the earlier filing date of prior application Serial No. 08/692,060, which was filed on August 2, 1996, and which is presently pending.

Each of these cited documents was submitted to, and/or cited by, the U.S. Patent and Trademark Office in connection with the '060 application. Therefore, in accordance with 37 C.F.R. § 1.98, copies of these references are not required to be provided in this application. To that end, copies of references AA-AU (U.S. Patents) are not enclosed herein. However, for the Examiner's convenience, copies of references BA-BE ("Foreign Patent Documents") and CA-CE ("Other Documents") are enclosed.

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U.S. Serial No.: 10/082,004  
Applicants: D. Baldwin, et al.  
Filing Date: February 22, 2002  
Art Unit: 1764  
Examiner: Not Yet Known

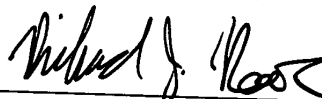
The enclosed Information Disclosure Statement is being filed prior to the mailing date of a first Office Action on the merits. Accordingly, Applicant(s) believes that no fee or certification is required.

No costs are believed to be due in connection with the filing of this Information Disclosure Statement. However, please charge any fees necessary to Deposit Account No. 04-1105.

Date: July 19, 2002

Respectfully submitted,

By:



Richard J. Roos, Esq.

Reg. No. 45,053

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**FORM PTO-1449**  
**INFORMATION DISCLOSURE**  
**STATEMENT**



**DOCKET NO.:**

70257/40535-RE-C

**SERIAL NO.:**

10/082,044

**APPLICANT(S):**

Daniel F. Baldwin, et al.

**FILING DATE:**

February 22, 2002

**GROUP NO.:**

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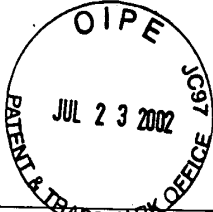
**UNITED STATES PATENT DOCUMENTS**

EXAM. INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	FILING DATE IF APPROPRIATE
	AA 3,227,664	01/04/66	Blades et al.			
	AB 3,227,784	01/04/66	Blades et al.			
	AC 3,796,779	03/12/74	Greenberg			
	AD 4,390,332	06/28/93	Hendry			
	AE 4,424,287	01/03/84	Johnson et al.			
	AF 4,455,272	06/19/84	Schubert et al.			
	AG 4,473,665	09/25/84	Martini-Vvedensky et al.			
	AH 4,548,775	10/22/85	Hayashi et al.			
	AI 4,628,559	03/01/88	Hardenbrook et al.			
	AJ 4,719,246	01/19/88	Murdoch et al.			
	AK 4,728,559	03/01/88	Hardenbrook et al.			
	AL 4,746,477	05/24/88	Wecker et al.			
	AM 4,761,256	08/02/88	Hardenbrook et al.			
	AN 4,832,881	05/23/89	Arnold, Jr., et al.			
	AO 4,873,218	10/10/89	Pekala et al.			
	AP 4,906,672	03/06/90	Stone et al.			
	AQ 5,064,587	11/12/91	Meyke et al.			
	AR 5,120,559	06/09/92	Rizvi et al.			
	AS 5,160,674	11/03/92	Colton et al.			
	AT 5,250,577	10/05/93	Welsh			
	AU 5,266,605	11/30/93	Welsh			

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**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES/NO
	BA EP 0376064 A2	04/07/90	Miyakawa et al.			
	BB EP 0707935 A2	04/24/96	Baumgart			
	BC WO 92/17533	10/15/92	Cha et al.			
	BD WO 90/07546	07/12/90	Chum et al.			
	BE WO 95/24440	09/14/95	Sanvasi			

<b>FORM PTO-1449</b> <b>INFORMATION DISCLOSURE</b> <b>STATEMENT</b>		<b>DOCKET NO.:</b> 470257/40535-RE-C	<b>SERIAL NO.:</b> 10/082,044
		<b>APPLICANT(S):</b> Daniel F. Baldwin, et al.	
		<b>FILING DATE:</b> February 22, 2002	<b>GROUP NO.:</b> 1764
<b>OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)</b>			
<b>EXAM. INITIALS</b>			
	CA	Baldwin, D.F., et al., "A PROCESSING SYSTEM FOR THE EXTRUSION OF MICROCELLULAR POLYMER SHEETS:..." Cellular and Microcellular Materials, MD-vol. 53:85-107 (ASME 1994).	
	CB	LeMay, J.D., et al. "LOW DENSITY MICROCELLULAR MATERIAL," MRS Bulletin, December 1990, pp 19-45.	
	CC	Cha, S.W., "A MICROCELLULAR FOAMING/FORMING PROCESS PERFORMED AT AMBIENT TEMPERATURE AND A TEMPERATURE AND A SUPER-MICROCELLULAR FOAMING PROCESS," (M.I.T.) 1994).	
	CD	Baldwin, D.F., "MICROCELLULAR POLYMER PROCESSING AND THE DESIGN OF A CONTINUOUS SHEET PROCESSING SYSTEM," Chapter *, pp. 204-205, and 241, (M.I.T. 1994).	
	CE	Park, C.B., "THE ROLE OF POLYMER/GAS SOLUTIONS IN CONTINUOUS PROCESSING OF MICROCELLULAR POLYMERS," Ch VII, pp. 128-130.	
<b>EXAMINER:</b>		<b>DATE:</b>	

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